

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	 STMicroelectronics International N.V
1.2 PCN No.	MDG/24/14421
1.3 Title of PCN	ST MUAR (Malaysia) additional source for STM32L0x in LQFP 7x7 48L package - on listed products
1.4 Product Category	STM32L05x, STM32L06x, STM32L07x, STM32L08x, STM32L0Bx
1.5 Issue date	2024-02-14

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.2.2 Marketing Manager	Veronique BARLATIER
2.2.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	ST Muar (Malaysia)

4. Description of change

	Old	New
4.1 Description	Back-end sources: - Stats ChipPAC JSCC Jiangyin China - ASE Kaohsiung Taiwan	Back-end sources: - Stats ChipPAC JSCC Jiangyin China - ASE Kaohsiung Taiwan - ST Muar Malaysia (extended capacity with additional assembly line)
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	No Impact on Form, Fit or Function	

5. Reason / motivation for change

5.1 Motivation	Due to the success on the market of STM32 devices, ST General Purpose Microcontrollers sub-group decided to qualify an additional back-end site to maintain state of the art service level to our customers thanks to extra capacity.
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	Change is visible in the marking. Please refer to PCN 14421 – Additional information attached document.
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7. Timing / schedule

7.1 Date of qualification results	2024-02-08
7.2 Intended start of delivery	2024-04-10
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	14421 MDG-MCD RER1514 V2- LQFP7x7 Muar-PCN9484 PCN14421 - reliability evaluation report.pdf
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8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2024-02-14
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9. Attachments (additional documentations)

14421 Public product.pdf
 14421 MDG-MCD RER1514 V2- LQFP7x7 Muar-PCN9484 PCN14421 - reliability evaluation report.pdf
 14421 PCN14421_Additional information.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32L051C6T6	
	STM32L051C6T6TR	
	STM32L051C8T3	
	STM32L051C8T6	
	STM32L051C8T6TR	
	STM32L051C8T7	
	STM32L052C6T6	
	STM32L052C8T6	
	STM32L053C6T6	
	STM32L053C6T7	
	STM32L053C8T6	
	STM32L053C8T6TR	
	STM32L053C8T7	
	STM32L063C8T6	
	STM32L071C8T6	
	STM32L071C8T6TR	
	STM32L071C8T7	
	STM32L071CBT3	
	STM32L071CBT6	
	STM32L071CBT6TR	
	STM32L071CBT7	
	STM32L071CZT3	
	STM32L071CZT6	
	STM32L071CZT6TR	
	STM32L071CZT7	
	STM32L072CBT6	
	STM32L072CZT6	
	STM32L072CZT6TR	
	STM32L072CZT7	
	STM32L073CBT6	
	STM32L073CZT3	
	STM32L073CZT6	
	STM32L081CBT6	
	STM32L081CZT6	
	STM32L083CBT6	
	STM32L083CZT6	

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MMS- MCD RER1514

Reliability Report

Qualification Type : ASSEMBLY LINE QUALIFICATION, NEW BILL OF MATERIALS

LQFP 7x7 48L - ST Muar Qualification

Capacity increase

(PCN 9484)
(PCN 14421)

Product / Process & Package Information	Die 410	Die 427	Die 765
Commercial Product:	STM32F103CBT6	STM32L152CCT6	STM8S207C8T6
Product Line:	STM32F die 410	STM32L die 427	STM8S die 765
Product Description:	Micro 32Bits		Micro 8Bits
Finish Good Code:	ES32F103CBT6\$J8	ES32L152CCT6\$B6	ES8S207C8T6\$9C
Mask Set Revision:	X410XXXX	X427XXXV	X765XXXV
Silicon Process Technology:	0.18 M8 EMBEDDED FLASH	8X - CMOSF9S	2V - CMOSF9
Wafer Fabrication Location:	TSMC Fab 3 Taiwan	ST Rousset 8 France	ST Rousset 8 France
Electrical Wafer Sort Test Plant Location:	ST MICROELECTRONICS Ang Mo Kio EWS SINGAPORE		ARDENTEC Hsinchu EWS Taiwan
Package:	LQFP 48 7x7x1.4		
Assembly Plant location:	ST Muar (Malaysia)		
Final Test plant location:	ST Muar (Malaysia)		

Approval List - Rev 1			
Function	Location	Name	Date
Division Q&R Responsible	ST Rousset	Gisèle SEUBE	May31st, 2016
Division Quality Manager	ST Rousset	Pascal NARCHE	May31st, 2016

Approval List – Rev2

Function	Location	Name	Date
GPM BE Q&R Manager	ST Rousset	Bérangère ROUTIER SCAPUCCI	February 08th, 2024
Subgroup Quality Manager	ST Rousset	Pascal NARCHE	February 08th, 2024

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1 RELIABILITY RESULTS OVERVIEW

1.1 Objectives

This report summarizes the reliability results for LQFP 48 7x7 package manufactured at ST Muar (Malaysia).

Test vehicles are described here below:

Product	Package
STM32F103CBT6	LQFP 48 7x7x1.4
STM32L152CCT6	LQFP 48 7x7x1.4
STM8S207C8T6	LQFP 48 7x7x1.4

1.2 Context

Due to the success on the market of STM32 devices, ST General Purpose Microcontrollers sub-group decided to increase capacity in order to maintain state of the art service level to our customers.

PCN9484 changes (added High Density line in ST Muar (Malaysia) assembly site, for LQFP 48 7x7 products) are described here below:

	Existing Bill Of Materials			Added Bill Of Materials
	STATS Shanghai (China)	ChipPAC	Amkor ATP (Philippines)	ST Muar (Malaysia)
Assembly site				ST Muar (Malaysia)
Wire	Gold 0.8mil		Gold 0.8mil	Silver 0.8mil
Leadframe	Copper Spot Ag	Frame	Copper Frame Spot Ag	Pre Plated Frame
Leadfinishing (*1)	Pure Tin (e3)		Pure Tin (e3)	Rough Ni Pd AgAu (e4)
Resin	Sumitomo G700E		Sumitomo G631HQ	Sumitomo G700LS
Glue	Ablestik 3230		Evertech AP4200	Hitachi EN4900

PCN14421 changes (additional source for STM32L0x in LQFP 7X7 48L package) are described here below:

		Existing back-end lines	Added back-end line
Assembly site		ASE KaoHsiung (Taiwan) STATSChipPAC JSCC (China)	ST Muar (Malaysia)
Leadframe		Copper frame spot Ag	Pre-Plated Copper Frame
Leadfinishing ⁽¹⁾		Pure tin (e3)	μ PPF (e4)
Molding Compound ⁽²⁾		Sumitomo EME-G631SH	Sumitomo EME-G631SHQ
Bonding Wire		gold 2N 0.8 MIL	Ag 96.5% 0.8 MIL
Die Attach Glue		Sumitomo CRM 1076WA	Ablestik 3230
Marking Composition		No 2D marking	2D Marking

⁽¹⁾ Lead color and surface finish change depending on ~~leadfinishing~~.

⁽²⁾ Package darkness changes depending on molding compound.



Listed products (die 417 – ex: STM32L05x, STM32L06x) (die 447 – ex: STM32L07x, STM32L08x) are qualified by similarity with test vehicle die 427 as same Diffusion process (F9GO2S).

According to the positive reliability results, the qualification is granted for High Density assembly line in ST Muar (Malaysia) for listed products in PCNs.

2 RELIABILITY TEST VEHICLES Characteristics

2.1 Reliability Test vehicles description

Package line	Assembly Line	Package	Device (Partial RawLine Code)	Diffusion Process	Number of Lots
HD LQFP	LQFP7*7	48L	STM8S (5B*765) STM32F (5B*410) STM32L (5B*427)	F9GO1 TSMC 0.18 μ m F9GO2S	1 1 1

2.2 Reliability Information

Lot ID	Lot 1	Lot 2	Lot 3
Die Name /cut:	410	427	765
Diffusion Lot Number:	93537129	VG536347	VG540309
Trace Code:	995510CH	995510CQ	995510CR
Assy lot number	995510CH01	995510CQ01	995510CR01

Raw Line Code	J55B*410ESXX	U05B*427ESXV	J15B*765ESXV
Reliability Lab location :	ST Muar (Malaysia)		

2.3 Front-End information

Front-End	Lot 1 (410)	Lot 2 (427)	Lot 3 (765)
Wafer Diameter:	8 inches		
Wafer Thickness:	375 +/-25 µm		
Die Size:	3.3908 X 3.328 mm	3.263 X 4.199 mm	3.010 X 2.458 mm
Scribe Line size x/y:	80 x 80 µm		
Pad Die Size /Pad type:	59 x 123 µm	53 x 108 µm	65 x 108 µm
Metal Layers Number /Materials /Thickness:	Metal 1 Tin/AlCu/Tin 0.450 µm Metal 2 Tin/AlCu/Tin 0.450 µm Metal 3 Tin/AlCu/Tin 0.450 µm Metal 4 Tin/AlCu/Tin 0.450 µm Metal 5 Tin/AlCu/Tin 0.875 µm	Metal 1 TaN/Ta/Cu 0.280 µm Metal 2 Ti/AlCu/TxTN 0.310 µm Metal 3 Ti/AlCu/TxTN 0.310 µm Metal 4 Ti/AlCu/TxTN 0.310 µm Metal 5 Ti/AlCu/TxTN 1.200 µm	Metal 1 TaN/Ta/Cu 0.280 µm Metal 2 TaN/Ta/Cu 0.350 µm Metal 3 TaN/Ta/Cu 0.350 µm Metal 4 Ti/AlCu/TxTN 0.900 µm
Passivation Layers Thickness:	HDPOx 10kA+SRO 1.5kA+PESIN 6kA		
Back Metal Finishing	RAW SILICON - BACK GRINDING		

2.4 Back-End information

Back-End	Lot 1 (410)	Lot 2 (427)	Lot 3 (765)		
Assembly Plant Location/ Address:	ST MICROELECTRONICS TANJONG AGAS IND ESTATE PO BOX 28 84007 MUAR / JOHOR MALAYSIA				
Die Thickness after Back grinding:	NA	NA	NA		
Die sawing method:	Step cut				
Die attach material:	Glue EN4900				
Type:	ST16				
Supplier:	Hitachi				
Lead frame material:	Copper LF-HD LQFP 48L 7x7	Copper LF-HD LQFP 48L 7x7			
L/F Finishing Type:	Rough µPPF (e4) Ni Pd AuAg	Rough µPPF (e4) Ni Pd AuAg			
Die paddle size:	5 x 5	3.6 x 3.6			
Supplier:	HDS	HDS			
Wire bonding:	AG 96,5% WIRE 0.8MIL MKE				
Type /Diameter:					
Supplier:					
Pitch:	80µm	70µm	80,36µm		
POA:	0110596				
Molding Compound Supplier:	EME-G700LS SUMITOMO				
Package Moisture Sensitivity Level (JEDEC J-STD020D):	2				

3 RELIABILITY RESULTS SUMMARY

3.1 Die oriented test

Description	Die Related Tests					Results LQFP 7x7		
	Test/Method	Conditions	Sample Size	Criteria	Readout / Duration	410	427	765
<i>Electrostatic discharge – Charge Device Model</i>								
ESD CDM	ANSI/ESD STM5.3.1	500V 1KV	3 units	500V for dice 410/427 1KV for 765	NA	0/3	0/3	0/3

3.2 Package Oriented Test

Description	Package Related Tests					Results LQFP 7x7		
	Test/Method	Conditions	Sample Size	Criteria	Readout / Duration	410	427	765
<i>Preconditioning: moisture sensitivity level 1</i>								
PC	J-STD-020 JESD22-A113	MSL1 For MSL2 Qual	308 units	Electrical test: A0/R1 (Accepted 0 reject/ Rejected 1 reject)	NA	0/308		
<i>High Temperature Storage Life</i>								
HTSL	JESD 22-A103	150°C	77 units	Elect test A0/R1	1000h	0/77	0/77	0/77
<i>Thermal Cycling after Preconditioning</i>								
TC	JESD 22-A104	-65c/+150°C	77 units	Elect test A0/R1	100cy	0/77	0/77	0/77
					500cy	0/77	0/77	0/77
					1000cy	0/77	0/77	0/77
<i>Wire Bond Shear after Thermal Cycling</i>								
Wire Bond Shear	AEC Q100-001	Min bond shear 15g after TC	30 x 3	A0/R1	After TC 500cy TC 1000cy	0/30	0/30	0/30
<i>Wire Bond Pull after Thermal Cycling</i>								
Wire Bond Pull	Mil Std 883 Method 2011	Minimum pull strength after TC=3 grams after TC	30 x 3	A0/R1	After TC 500cy TC 1000cy	0/30	0/30	0/30
<i>Autoclave after Preconditioning</i>								

AC	JESD 22A102	121°C ,100% 2Atm RH	77 units	Elect test A0/R1	96h	0/77	0/77	0/77
<i>Temperature Humidity Bias after Preconditioning</i>								
THB	JESD 22A110	85°C/85%RH Bias	77 units	Elect test A0/R1	1000h	0/77	0/77	0/77
<i>Construction Analysis</i>								
CA	Construction Analysis including : -Wire bond shear -Wire bond pull -Solderability -Physical Dimension	JESD 22B102 JESDB100/B108	50		No major concern	No major concern		

4 APPLICABLE AND REFERENCE DOCUMENTS

ADCS/DMS 0061692 :	Reliability Tests And Criteria For Qualifications
SOP 2.6.2:	Process qualification and transfer management
SOP 2.6.7:	Product Maturity Level
SOP 2.6.9:	Package and process maturity management in Back End
SOP 2.6.11:	Program management from product qualification
SOP 2.6.19:	Process maturity level
ANSI-ESD STM5.3.1:	Electrostatic discharge (ESD) sensitivity testing charge device model (CDM)
JESD 22-A103	High Temperature Storage Life
J-STD-020D:	Moisture/reflow sensitivity classification for non-hermetic solid state surface mount devices
JESD22-A113:	Preconditioning of non-hermetic surface mount devices prior to reliability testing
JESD22-A102:	Autoclave test (pressure pot)
JESD22-A104:	Temperature cycling
JESD22-A110:	Temperature Humidity Bake
JESD 22B102:	Solderability test
JESD22B100/B108:	Physical dimension

5 GLOSSARY AND TESTS DESCRIPTION

PC	Preconditioning (solder simulation)
THB	Temperature Humidity Bias
TC	Temperature cycling
AC	Autoclave test (pressure pot)
HTSL	High temperature storage life
ADCS/DMS	ST Advanced Documentation Controlled system/ Documentation Management system
ESD CDM	Electrostatic discharge (charge device model)
CA	Construction Analysis

6 REVISION HISTORY

Version	Date	Author	Comment
1.0	May 31st, 2016	Olivier GIRAUD	Initial release for qualification
2.0	February 08 th , 2024	Lionel NEVORET	additional source for STM32L0x in LQFP 7X7 48L package

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**PRODUCT/PROCESS
CHANGE NOTIFICATION
PCN14421
– Additional information**

**ST MUAR (Malaysia) additional source for STM32L0x in LQFP
7X7 48L package - on listed products**

MDG - General Purpose Microcontroller Division (GPM)

What are the changes?

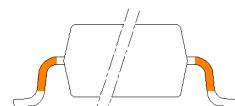
ST General Purpose Microcontrollers Division decided to qualify an additional back-end assembly site. The full process transfer to ST MUAR Assembly site is done maintaining state of the art service level to our customers thanks to extra capacity. This PCN is limited to STM32L0x listed products in LQFP 7x7 48L package.

Changes are described in table below:

Assembly site	Existing back-end lines		Added back-end line
ASE KaoHsiung (Taiwan)	STATSChipPAC JSCC (China)		ST Muar (Malaysia)
Copper frame spot Ag	Copper Frame Spot Ag		Pre-Plated Copper Frame
Pure tin (e3)	Pure tin (e3)		μ PPF (e4)
Sumitomo EME-G631SH	Sumitomo EME-G631SHQ		Sumitomo EME-G700LS
gold 2N 0.8 MIL	Ag 96.5% 0.8 MIL	Gold 0.8 MIL	Ag 96.5% 0.8 MIL
Sumitomo CRM 1076WA	Ablestik 3230		Hitachi EN4900
No 2D marking	No 2D marking		2D Marking

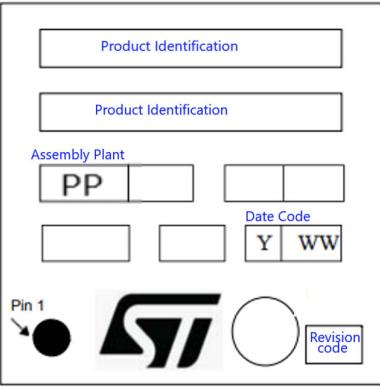
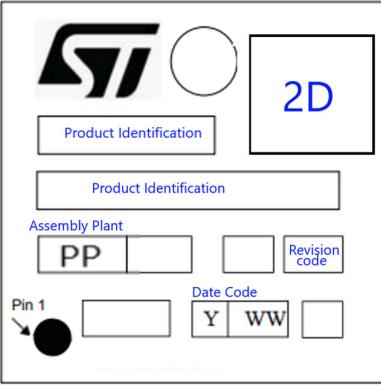
(1) Lead color and surface finishing may slightly vary depending on leadfinishing.

(2) Package darkness or chromaticity may change depending on molding compound.



Pin1 identifier may change in terms of size and positioning however remaining near pin1's edge. Marking position and size may be different upon assembly site, without any loss of information.

How can the change be seen?

Marking	Existing	Added Back-End Site
LQFP 7x7 48L		
PP code	AA: ASE KaoHsiung (Philippines) GQ: Stats ChipPAC JSCC (China)	9H: ST MUAR (Malaysia)

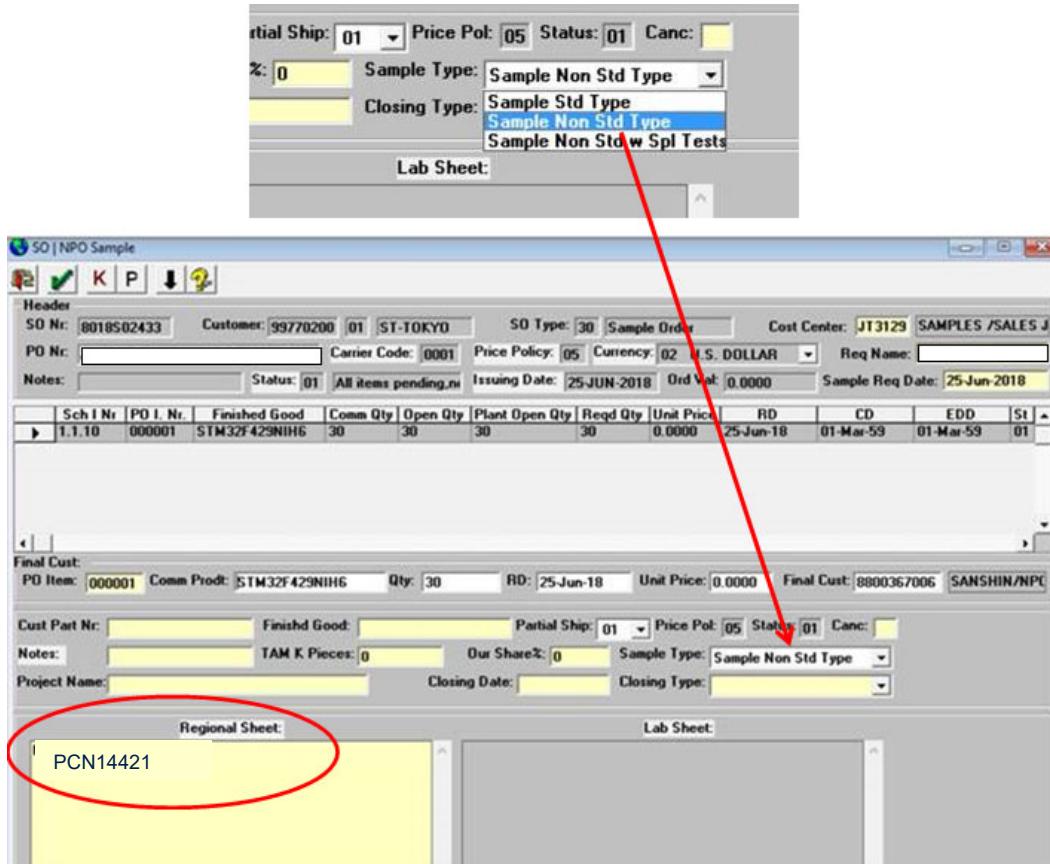
Y WW code indicates Year Week (manufacturing date)

PP code indicates assembly traceability plant code.

How to order samples?

For all samples request linked to this PCN, please:

- place a **Non-standard** sample order (choose Sample Non Std Type from pull down menu)
- insert the PCN number “**PCN14421**” into the NPO Electronic Sheet/**Regional Sheet**
- request sample(s) through Notice tool, indicating a single Commercial Product for each request



SO | NPO Sample

Header

SO Nr: 0018502433 Customer: 99770200 01 ST-TOKYO SO Type: 30 Sample Order Cost Center: JT3129 SAMPLES /SALES J

PO Nr: Carrier Code: 0001 Price Policy: 05 Currency: 02 U.S. DOLLAR Req Name:

Notes: Status: 01 All items pending, no Issuing Date: 25-JUN-2018 Ord Val: 0.0000 Sample Req Date: 25-Jun-2018

Sch I Nr	PO I. Nr.	Finished Good	Coms Qty	Open Qty	Plant Open Qty	Reqd Qty	Unit Price	RD	CD	EDD	St
1.1.10	000001	STM32F429NIH6	30	30	30	30	0.0000	25-Jun-18	01-Mar-53	01-Mar-53	01

Final Cust:

PO Item: 000001 Comm Prod: STM32F429NIH6 Qty: 30 RD: 25-Jun-18 Unit Price: 0.0000 Final Cust: 8800367006 SANSHIN/NPC

Cust Part Nr: Finished Good: Partial Ship: 01 Price Pol: 05 Status: 01 Canc:

Notes: TAM K Pieces: 0 Our Share%: 0 Sample Type: Sample Non Std Type

Project Name: Closing Date: Closing Type:

Regional Sheet: PCN14421

Lab Sheet:



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PCN Title : ST MUAR (Malaysia) additional source for STM32L0x in LQFP 7X7 48L package - on listed products

PCN Reference : MDG/24/14421

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STM32L071C8T6TR	STM32L053C8T7	STM32L051C8T6
STM32L073CZT3	STM32L083CZT6	STM32L081CZT6
STM32L071CZT3TR	STM32L072CZT6TR	STM32L052C8T6
STM32L053C8T3	STM32L052C8T6TR	STM32L052C6T6
STM32L071CZT3	STM32L051C8T7	STM32L072CZT7
STM32L071CBT6	STM32L071CBT3TR	STM32L073CZT6
STM32L071CZT6TR	STM32L053C6T7	STM32L071CBT6TR
STM32L052C8T7	STM32L081CBT6TR	STM32L053C8T6
STM32L072CBT6TR	STM32L071CBT3	STM32L072CZT7TR
STM32L051C8T6TR	STM32L073CBT6	STM32L073CBT6TR
STM32L053C8T6TR	STM32L063C8T6	STM32L051C6T6
STM32L053C6T6	STM32L071CBT7	STM32L072CZT6
STM32L051C8T7TR	STM32L051C8T3	STM32L072CBT6
STM32L071CZT7	STM32L083CZT6TR	STM32L051C6T6TR
STM32L071C8T7	STM32L071CZT6	STM32L071C8T6
STM32L083CBT6	STM32L081CBT6	

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